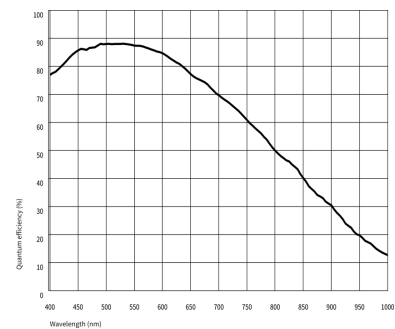


In series
The model is in series and available for the long term.



Specification

Sensor	
Sensor type	CMOS Mono
Shutter	Global Shutter
Sensor characteristic	Linear
Pixel Class	3 MP
Resolution	3.20 Mpix
Resolution (h x v)	2064 x 1552 Pixel
Aspect ratio	4:3
ADC	12 bit
Color depth (camera)	12 bit
Optical sensor class	1/3.1"
Optical Size	4.644 mm x 3.492 mm
Optical sensor diagonal	5.81 mm 1/3.1"
Pixel size	2.25 µm
CRA (Chief Ray Angle)	8 °
Manufacturer	Sony
Sensor Model	IMX900-AMR-C
Gain (master/RGB)	15.8x/-
AOI horizontal	same frame rate
AOI vertical	increased frame rate
AOI image width / step width	264 / 24
AOI image height / step width	16 / 8
AOI position grid (horizontal/vertical)	8 / 8
Binning horizontal	increased frame rate
Binning vertical	increased frame rate
Binning method	Horizontal: mean / Vertical: mean
Binning factor	2x2
Decimation (subsampling) horizontal	-
Decimation (subsampling) vertical	-
Decimation (subsampling) method	-



Model

Frame rate freerun mode	67 fps
Frame rate trigger (continuous)	70 fps
Frame rate trigger (maximum)	70 fps
Exposure time (minimum - maximum)	0.016 ms - 1999 ms
Power consumption	0.5 W - 1 W
Image memory	-

HDR

Mode	QuadHDR
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Ambient conditions

The temperature values given below refer to the outer device temperature of the camera housing.

Allowed device temperature during operation	0 °C - 55 °C / 32 °F - 131 °F
Allowed ambient temperature during operation	0 °C - °C / 32 °F - 32 °F
Allowed ambient temperature during storage	-20 °C - 60 °C / -4 °F - 140 °F
Humidity (relative, non-condensing)	20 % - 80 %

Connectors

Interface connector	USB 3.0 micro-B, screwable
I/O connector	8-pin Wuerth connector
Power supply	USB cable

Pin assignment I/O connector

1	Voltage output 3.3 V
2	Ground (GND)
3	Flash output without optocoupler - Line 1
4	Trigger input without optocoupler - Line 0
5	General Purpose I/O (GPIO) 1 - Line 2
6	General Purpose I/O (GPIO) 2 - Line 3
7	Ground (GND)
8	USB Power: 5 V, max. 400 mA



Design

Lens Mount	C-Mount
IP code	IP30
Dimensions H/W/L	29.0 mm x 29.0 mm x 17.0 mm
Mass	62 g
Housing material	Zinc nickel-plated

Features

List of on-camera image pre-processing features.

All features of the table are available via our IDS peak software for image pre-processing on the host computer (sensor model dependent).

Image Acquisition	Freerun	✓
	Software trigger	✓
	Hardware trigger	✓
	Trigger controlled exposure	-
	Denoiser	-
	Long exposure	-
	Line scan	-

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Flashing	Flashing	✓
	PWM flashing	-
Image Adjustments	Auto exposure	-
	Auto gain	-
	Auto whitebalance	-
	Color correction	-
	Gamma	-
	LUT	-
	Mirror/flip	X/Y
On-board Image Processing	Pixel formats	Mono8 Mono10g40IDS Mono12g24IDS
	Region of interest	✓
	Decimation (FPGA)	-
	Decimation (Sensor)	
	Binning (FPGA)	-
	Binning (Sensor)	2x2 Increases frame rate.
Others	Chunks	-
	Sequencer	-
	Events	-
	Firmware update	✓
	1st supported firmware version	3.62.25422